



Amkor's Edge Protection™ Technology

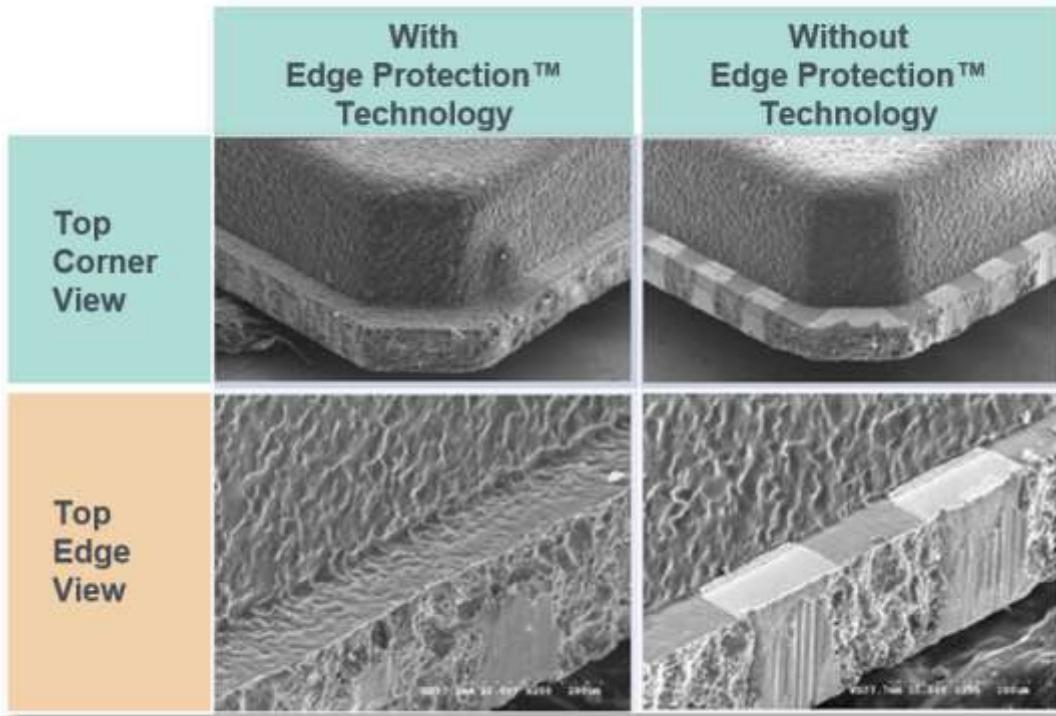
Innovative Enhancement for Automotive Packaging

Amkor has improved the robustness of the [MicroLeadFrame®](#) (MLF®/QFN) package [design](#) with the development of Edge Protection™ technology. This advancement protects the edges of the device during [test](#) and Surface Mount Assembly (SMA) handling operations.

This innovative package enhancement strengthens the edges of the punch MLF package, resulting in a significant reduction in test and assembly induced damage. Amkor's Edge Protection™ technology is available now on punch MLF packages in a variety of body sizes.

Benefits include:

- Significantly reduced possibility of gaps/cracks resulting from mechanical stress and offers added protection for all handling procedures
- Greatly improved package strength and provides robust performance during burn-in and electrical ATE test insertions
- Eliminates Surface Mount Technology related incidents since placement equipment only touches Epoxy Molding Compound (EMC), with no contact of the leadframe during placement



Related Downloads:

- Edge Protection™ Technology Datasheet - [EN](#), [KR](#), [JP](#), [CN](#)
- MicroLeadFrame® Datasheet - [EN](#), [KR](#), [JP](#), [CN](#)
- [Enhancing Punch MLF® Packaging with Edge Protection Technology White Paper - EN](#)

[Contact our sales team](#) to add Amkor's Edge Protection™ Technology to your MLF®/QFN packages.